

10/090, 806

L Number	Hits	Search Text	DB	Time stamp
1	6394	thermistor and (negative ntc) and (positive ptc) and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/28 12:42
2	545	(thermistor and (negative ntc) and (positive ptc) and @ad<19991019) and inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/28 12:43
3	152	((thermistor and (negative ntc) and (positive ptc) and @ad<19991019) and inductor) and module	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/28 12:44
4	21	((thermistor and (negative ntc) and (positive ptc) and @ad<19991019) and inductor) and module) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/28 12:44
-	991	inductor and thermistor and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/28 10:49
-	14	(inductor and thermistor and @ad<19991019) and (ceramic near4 laminat\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/27 10:25
-	991	inductor and thermistor and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/27 10:09
-	177	(inductor and thermistor and @ad<19991019) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/27 10:09
-	17	((inductor and thermistor and @ad<19991019) and ceramic) and diffusion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/27 10:09
-	14	(inductor and thermistor and @ad<19991019) and (ceramic near4 laminat\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/27 15:08
-	14	(inductor and thermistor and @ad<19991019) and (ceramic near4 laminat\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/27 15:35
-	0	module near6 (inductor and thermistor) and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/27 15:38
-	0	(module board substrate mcm) near6 (inductor and thermistor) and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/27 15:40

10/090.806

	70	(module board substrate mcm) same (inductor and thermistor) and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/27 15:53
	70	((module board substrate mcm) same (inductor and thermistor)) and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/27 15:58
	361	(361/729).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/27 15:59
	252	((361/729).CCLS.) and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/27 15:59
	0	((361/729).CCLS.) and @ad<19991019) and inductor and thermistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/27 15:59
	991	inductor and thermistor and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/27 16:00
	49	(inductor and thermistor and @ad<19991019) and diffusion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/27 20:44
	2	("5796568").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/27 20:44
	2492	((361/106) or (361/58) or (361/111)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/28 10:49
	1789	((361/106) or (361/58) or (361/111)).CCLS.) and @ad<19991019	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/28 10:50
	14	((361/106) or (361/58) or (361/111)).CCLS.) and @ad<19991019) and thermistor and inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/28 12:40